



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC057N03LS G		<b>Issued</b>		25. January 2018		
<b>MA#</b>		MA001816448						
<b>Package</b>		PG-TDSON-8-40		<b>Weight*</b>		111.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.076	0.96	0.96	9628	9628
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		131	
	non noble metal	iron	7439-89-6	0.049	0.04		436	
	non noble metal	copper	7440-50-8	48.649	43.53	43.58	435125	435692
	non noble metal	copper	7440-50-8	0.061	0.05	0.05	542	542
wire	non noble metal	copper	7440-50-8	0.061	0.05	0.05	542	542
encapsulation	organic material	carbon black	1333-86-4	0.084	0.08		752	
	plastics	epoxy resin	-	6.642	5.94		59405	
	inorganic material	silicondioxide	60676-86-0	35.311	31.58	37.60	315822	375979
leadfinish	non noble metal	tin	7440-31-5	1.520	1.36	1.36	13595	13595
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1417	1417
solder	non noble metal	tin	7440-31-5	0.026	0.02		234	
	noble metal	silver	7440-22-4	0.033	0.03		293	
	non noble metal	lead	7439-92-1	1.250	1.12	1.17	11178	11705
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	16.910	15.12	15.14	151246	151442
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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